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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	HCS12
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, I²C, SCI, SPI
Peripherals	PWM, WDT
Number of I/O	59
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.25V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	80-QFP
Supplier Device Package	80-QFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s12d64cfue

Version Number	Revision Date	Effective Date	Author	Description of Changes
V01.15	22 July 2003	22 July 2003		Mentioned "S12 LRAE" bootloader in Flash section Section Document References: corrected S12 CPU document reference
V01.16	24 Feb. 2004	24 Feb. 2004		Added 3L86D maskset with corresponding Part ID Table Oscillator Characteristics: Added more details for EXTAL pin
V01.17	21 May 2004	21 May 2004		Added 4L86D maskset with corresponding Part ID Table "MC9S12DJ64 Memory Map out of Reset": corrected $1000 - $3fff memory in single chip modes to "unimplemented".
V01.18	13 July 2004	13 July 2004		Added MC9S12D32 and MC9S12A32
V01.19	2 Sept. 2004	2 Sept. 2004		Appendix, Table "Oscillator Characteristics": changed item 13 VIH,EXTAL min value from 0.7*VDDPLL to 0.75*VDDPLL item 14 VIL,EXTAL max value from 0.3*VDDPLL to 0.25*VDDPLL
V01.20	6 April 2005	6 April 2005		Table "Assigned Part ID Numbers": added mask set number 0M89C Table "NVM Reliability Characteristics": added footnote concerning data retention

List of Tables

1.4 Block Diagram

Figure 1-1 shows a block diagram of the MC9S12DJ64 device.

Figure 1-1 MC9S12DJ64 Block Diagram

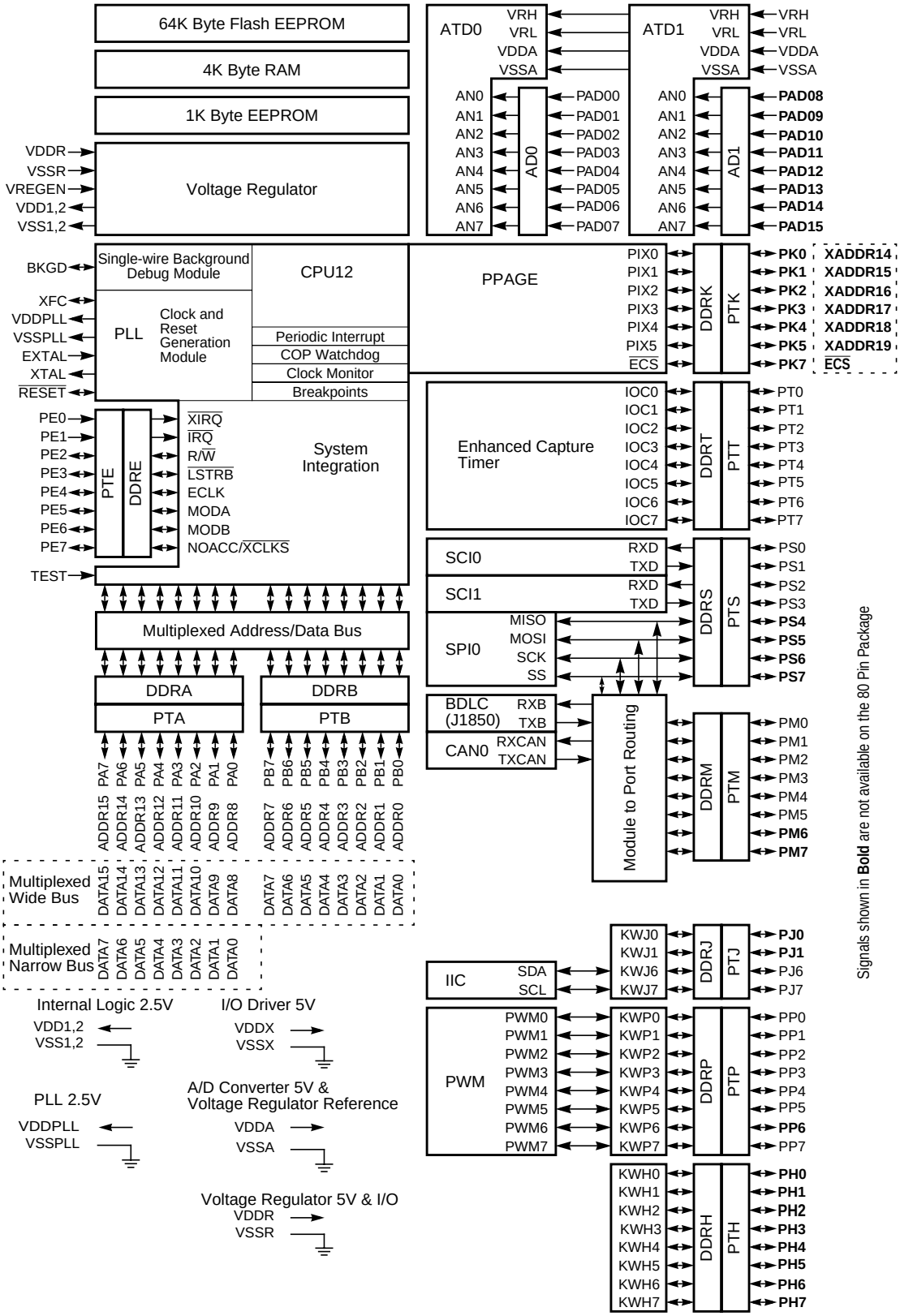


Table 1-1 Device Memory Map for MC9S12DJ64

Address	Module	Size (Bytes)
$C000 - $FFFF	Fixed Flash EEPROM array incl. 0.5K, 1K, 2K or 4K Protected Sector at end and 256 bytes of Vector Space at $FF80 - $FFFF	16384

$001F - $001F INT map 2 of 2 (HCS12 Interrupt)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$001F	HPRIO	Read:	PSEL7	PSEL6	PSEL5	PSEL4	PSEL3	PSEL2	PSEL1	0
		Write:								

$0020 - $0027 Reserved

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0020 - $0027	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

$0028 - $002F BKP (HCS12 Breakpoint)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0028	BKPCT0	Read:	BKEN	BKFULL	BKBDM	BKTAG	0	0	0	0
		Write:								
$0029	BKPCT1	Read:	BK0MBH	BK0MBL	BK1MBH	BK1MBL	BK0RWE	BK0RW	BK1RWE	BK1RW
		Write:								
$002A	BKP0X	Read:	0	0	BK0V5	BK0V4	BK0V3	BK0V2	BK0V1	BK0V0
		Write:								
$002B	BKP0H	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
$002C	BKP0L	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
$002D	BKP1X	Read:	0	0	BK1V5	BK1V4	BK1V3	BK1V2	BK1V1	BK1V0
		Write:								
$002E	BKP1H	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
$002F	BKP1L	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								

$0030 - $0031 MMC map 4 of 4 (HCS12 Module Mapping Control)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0030	PPAGE	Read:	0	0	PIX5	PIX4	PIX3	PIX2	PIX1	PIX0
		Write:								
$0031	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

$0032 - $0033 MEBI map 3 of 3 (HCS12 Multiplexed External Bus Interface)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0032	PORTK	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
$0033	DDRK	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								

$0034 - $003F CRG (Clock and Reset Generator)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0034	SYNR	Read:	0	0	SYN5	SYN4	SYN3	SYN2	SYN1	SYN0
		Write:								
$0035	REFDV	Read:	0	0	0	0	REFDV3	REFDV2	REFDV1	REFDV0
		Write:								
$0036	CTFLG TEST ONLY	Read:	0	0	0	0	0	0	0	0
		Write:								
$0037	CRGFLG	Read:	RTIF	PORF	0	LOCKIF	LOCK	TRACK	SCMIF	SCM
		Write:								
$0038	CRGINT	Read:	RTIE	0	0	LOCKIE	0	0	SCMIE	0
		Write:								
$0039	CLKSEL	Read:	PLLSEL	PSTP	SYSWAI	ROAWAI	PLLWAI	CWAI	RTIWAI	COPWAI
		Write:								
$003A	PLLCTL	Read:	CME	PLLON	AUTO	ACQ	0	PRE	PCE	SCME
		Write:								
$003B	RTICTL	Read:	0	RTR6	RTR5	RTR4	RTR3	RTR2	RTR1	RTR0
		Write:								
$003C	COPCTL	Read:	WCOP	RSBCK	0	0	0	CR2	CR1	CR0
		Write:								
$003D	FORBYP TEST ONLY	Read:	0	0	0	0	0	0	0	0
		Write:								
$003E	CTCTL TEST ONLY	Read:	0	0	0	0	0	0	0	0
		Write:								
$003F	ARMCOP	Read:	0	0	0	0	0	0	0	0
		Write:	Bit 7	6	5	4	3	2	1	Bit 0

$0040 - $007F ECT (Enhanced Capture Timer 16 Bit 8 Channels)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0040	TIOS	Read:	IOS7	IOS6	IOS5	IOS4	IOS3	IOS2	IOS1	IOS0
		Write:								
$0041	CFORC	Read:	0	0	0	0	0	0	0	0
		Write:	FOC7	FOC6	FOC5	FOC4	FOC3	FOC2	FOC1	FOC0
$0042	OC7M	Read:	OC7M7	OC7M6	OC7M5	OC7M4	OC7M3	OC7M2	OC7M1	OC7M0
		Write:								
$0043	OC7D	Read:	OC7D7	OC7D6	OC7D5	OC7D4	OC7D3	OC7D2	OC7D1	OC7D0
		Write:								
$0044	TCNT (hi)	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
$0045	TCNT (lo)	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
$0046	TSCR1	Read:	TEN	TSWAI	TSFRZ	TFFCA	0	0	0	0
		Write:								
$0047	TTOV	Read:	TOV7	TOV6	TOV5	TOV4	TOV3	TOV2	TOV1	TOV0
		Write:								
$0048	TCTL1	Read:	OM7	OL7	OM6	OL6	OM5	OL5	OM4	OL4
		Write:								
$0049	TCTL2	Read:	OM3	OL3	OM2	OL2	OM1	OL1	OM0	OL0
		Write:								

$00E8 - $00EF BDLC (Bytelevel Data Link Controller J1850)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$00E8	DLCBCR1	Read:	IMSG	CLKS	0	0	0	0	IE	WCM
		Write:								
$00E9	DLCBSVR	Read:	0	0	I3	I2	I1	I0	0	0
		Write:								
$00EA	DLCBCR2	Read:	SMRST	DLOOP	RX4XE	NBFS	TEOD	TSIFR	TMIFR1	TMIFR0
		Write:								
$00EB	DLCBDR	Read:	D7	D6	D5	D4	D3	D2	D1	D0
		Write:								
$00EC	DLCBARD	Read:	0	RXPOL	0	0	BO3	BO2	BO1	BO0
		Write:								
$00ED	DLCBRSR	Read:	0	0	R5	R4	R3	R2	R1	R0
		Write:								
$00EE	DLCSCR	Read:	0	0	0	BDLCE	0	0	0	0
		Write:								
$00EF	DLCBSTAT	Read:	0	0	0	0	0	0	0	IDLE
		Write:								

$00F0 - $00FF Reserved

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$00F0 - $00FF	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

$0100 - $010F Flash Control Register (fts64k)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0100	FCLKDIV	Read:	FDIVLD	PRDIV8	FDIV5	FDIV4	FDIV3	FDIV2	FDIV1	FDIV0
		Write:								
$0101	FSEC	Read:	KEYEN	NV6	NV5	NV4	NV3	NV2	SEC1	SEC0
		Write:								
$0102	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$0103	FCNFG	Read:	CBEIE	CCIE	KEYACC	0	0	0	0	0
		Write:								
$0104	FPROT	Read:	FPOPEN	NV6	FPHDIS	FPHS1	FPHS0	FPLDIS	FPLS1	FPLS0
		Write:								
$0105	FSTAT	Read:	CBEIF	CCIF	PVIOL	ACCERR	0	BLANK	0	0
		Write:								
$0106	FCMD	Read:	0	CMDB6	CMDB5	0	0	CMDB2	0	CMDB0
		Write:								
$0107	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$0108	FADDRHI	Read:	Bit 14	Bit 14	13	12	11	10	9	Bit 8
		Write:								
$0109	FADDRLO	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								

$0100 - $010F Flash Control Register (fts64k)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$010A	FDATAHI	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
$010B	FDATALO	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
$010C - $010F	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

$0110 - $011B EEPROM Control Register (eets1k)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0110	ECLKDIV	Read:	EDIVLD	PRDIV8	EDIV5	EDIV4	EDIV3	EDIV2	EDIV1	EDIV0
		Write:								
$0111	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$0112	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								
$0113	ECNFG	Read:	CBEIE	CCIE	0	0	0	0	0	0
		Write:								
$0114	EPROT	Read:	EPOPEN	NV6	NV5	NV4	EPDIS	EP2	EP1	EP0
		Write:								
$0115	ESTAT	Read:	CBEIF	CCIF	PVIOL	ACCERR	0	BLANK	0	0
		Write:								
$0116	ECMD	Read:	0	CMDB6	CMDB5	0	0	CMDB2	0	CMDB0
		Write:								
$0117	Reserved for Factory Test	Read:	0	0	0	0	0	0	0	0
		Write:								
$0118	EADDRHI	Read:	0	0	0	0	0	0	0	Bit 8
		Write:								
$0119	EADDRLO	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								
$011A	EDATAHI	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
$011B	EDATALO	Read:	Bit 7	6	5	4	3	2	1	Bit 0
		Write:								

$011C - $011F Reserved for RAM Control Register

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$011C - $011F	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

$0240 - $027F PIM (Port Integration Module)

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0263	RDRH	Read:	RDRH7	RDRH6	RDRH5	RDRH4	RDRH3	RDRH2	RDRH1	RDRH0
		Write:								
$0264	PERH	Read:	PERH7	PERH6	PERH5	PERH4	PERH3	PERH2	PERH1	PERH0
		Write:								
$0265	PPSH	Read:	PPSH7	PPSH6	PPSH5	PPSH4	PPSH3	PPSH2	PPSH1	PPSH0
		Write:								
$0266	PIEH	Read:	PIEH7	PIEH6	PIEH5	PIEH4	PIEH3	PIEH2	PIEH1	PIEH0
		Write:								
$0267	PIFH	Read:	PIFH7	PIFH6	PIFH5	PIFH4	PIFH3	PIFH2	PIFH1	PIFH0
		Write:								
$0268	PTJ	Read:	PTJ7	PTJ6	0	0	0	0	PTJ1	PTJ0
		Write:								
$0269	PTIJ	Read:	PTIJ7	PTIJ6	0	0	0	0	PTIJ1	PTIJ0
		Write:								
$026A	DDRJ	Read:	DDRJ7	DDRJ7	0	0	0	0	DDRJ1	DDRJ0
		Write:								
$026B	RDRJ	Read:	RDRJ7	RDRJ6	0	0	0	0	RDRJ1	RDRJ0
		Write:								
$026C	PERJ	Read:	PERJ7	PERJ6	0	0	0	0	PERJ1	PERJ0
		Write:								
$026D	PPSJ	Read:	PPSJ7	PPSJ6	0	0	0	0	PPSJ1	PPSJ0
		Write:								
$026E	PIEJ	Read:	PIEJ7	PIEJ6	0	0	0	0	PIEJ1	PIEJ0
		Write:								
$026F	PIFJ	Read:	PIFJ7	PIFJ6	0	0	0	0	PIFJ1	PIFJ0
		Write:								
$0270 - $027F	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

$0280 - $03FF Reserved

Address	Name		Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
$0280 - $03FF	Reserved	Read:	0	0	0	0	0	0	0	0
		Write:								

instruction queue. It is used as a MCU operating mode select pin during reset. The state of this pin is latched to the MODC bit at the rising edge of $\overline{\text{RESET}}$. This pin has a permanently enabled pull-up device.

2.3.7 PAD15 / AN15 / ETRIG1 — Port AD Input Pin of ATD1

PAD15 is a general purpose input pin and analog input AN7 of the analog to digital converter ATD1. It can act as an external trigger input for the ATD1.

2.3.8 PAD[14:08] / AN[14:08] — Port AD Input Pins ATD1

PAD14 - PAD08 are general purpose input pins and analog inputs AN[6:0] of the analog to digital converter ATD1.

2.3.9 PAD07 / AN07 / ETRIG0 — Port AD Input Pin of ATD0

PAD07 is a general purpose input pin and analog input AN0 of the analog to digital converter ATD0. It can act as an external trigger input for the ATD0.

2.3.10 PAD[06:00] / AN[06:00] — Port AD Input Pins of ATD0

PAD06 - PAD00 are general purpose input pins and analog inputs AN[6:0] of the analog to digital converter ATD0.

2.3.11 PA[7:0] / ADDR[15:8] / DATA[15:8] — Port A I/O Pins

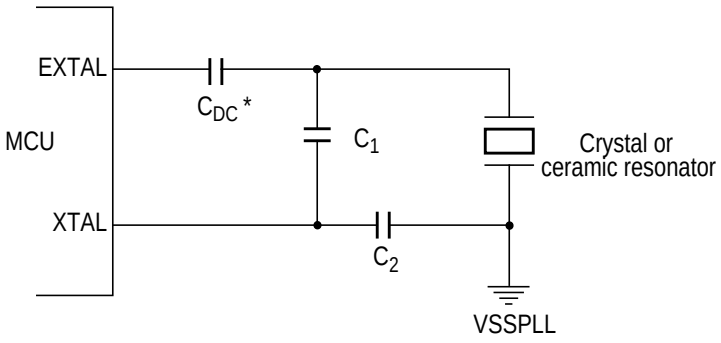
PA7-PA0 are general purpose input or output pins. In MCU expanded modes of operation, these pins are used for the multiplexed external address and data bus.

2.3.12 PB[7:0] / ADDR[7:0] / DATA[7:0] — Port B I/O Pins

PB7-PB0 are general purpose input or output pins. In MCU expanded modes of operation, these pins are used for the multiplexed external address and data bus.

2.3.13 PE7 / NOACC / $\overline{\text{XCLKS}}$ — Port E I/O Pin 7

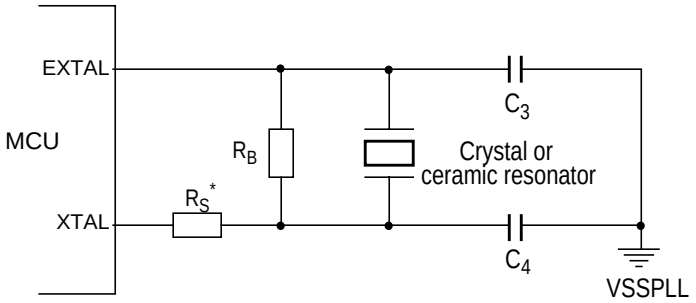
PE7 is a general purpose input or output pin. During MCU expanded modes of operation, the NOACC signal, when enabled, is used to indicate that the current bus cycle is an unused or “free” cycle. This signal will assert when the CPU is not using the bus.
The $\overline{\text{XCLKS}}$ is an input signal which controls whether a crystal in combination with the internal Colpitts (low power) oscillator is used or whether Pierce oscillator/external clock circuitry is used. The state of this pin is latched at the rising edge of $\overline{\text{RESET}}$. If the input is a logic low the EXTAL pin is configured for an external clock drive or a Pierce Oscillator. If input is a logic high a Colpitts oscillator circuit is configured on EXTAL and XTAL. Since this pin is an input with a pull-up device during reset, if the pin is left floating, the default configuration is a Colpitts oscillator circuit on EXTAL and XTAL.



* Due to the nature of a translated ground Colpitts oscillator a DC voltage bias is applied to the crystal

Please contact the crystal manufacturer for crystal DC bias conditions and recommended capacitor value C_{DC}.

Figure 2-4 Colpitts Oscillator Connections (PE7=1)



* Rs can be zero (shorted) when used with higher frequency crystals. Refer to manufacturer's data.

Figure 2-5 Pierce Oscillator Connections (PE7=0)

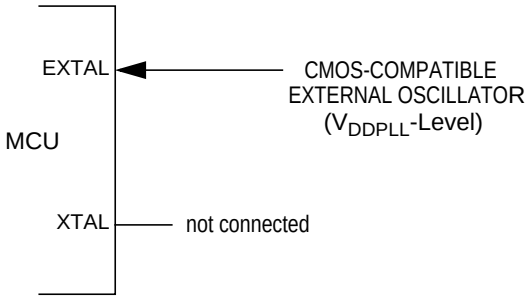


Figure 2-6 External Clock Connections (PE7=0)

4.3.2.2 Executing from External Memory

The user may wish to execute from external space with a secured microcontroller. This is accomplished by resetting directly into expanded mode. The internal FLASH and EEPROM will be disabled. BDM operations will be blocked.

4.3.3 Unsecuring the Microcontroller

In order to unsecure the microcontroller, the internal FLASH and EEPROM must be erased. This can be done through an external program in expanded mode or via a sequence of BDM commands. Unsecuring is also possible via the Backdoor Key Access. Refer to Flash Block Guide for details.

Once the user has erased the FLASH and EEPROM, the part can be reset into special single chip mode. This invokes a program that verifies the erasure of the internal FLASH and EEPROM. Once this program completes, the user can erase and program the FLASH security bits to the unsecured state. This is generally done through the BDM, but the user could also change to expanded mode (by writing the mode bits through the BDM) and jumping to an external program (again through BDM commands). Note that if the part goes through a reset before the security bits are reprogrammed to the unsecure state, the part will be secured again.

4.4 Low Power Modes

The microcontroller features three main low power modes. Consult the respective Block User Guide for information on the module behavior in Stop, Pseudo Stop, and Wait Mode. An important source of information about the clock system is the Clock and Reset Generator User Guide (CRG).

4.4.1 Stop

Executing the CPU STOP instruction stops all clocks and the oscillator thus putting the chip in fully static mode. Wake up from this mode can be done via reset or external interrupts.

4.4.2 Pseudo Stop

This mode is entered by executing the CPU STOP instruction. In this mode the oscillator is still running and the Real Time Interrupt (RTI) or Watchdog (COP) sub module can stay active. Other peripherals are turned off. This mode consumes more current than the full STOP mode, but the wake up time from this mode is significantly shorter.

4.4.3 Wait

This mode is entered by executing the CPU WAI instruction. In this mode the CPU will not execute instructions. The internal CPU signals (address and data bus) will be fully static. All peripherals stay active. For further power consumption the peripherals can individually turn off their local clocks.

NOTE: *Please refer to the temperature rating of the device (C, V, M) with regards to the ambient temperature T_A and the junction temperature T_J. For power dissipation calculations refer to* ***Section A.1.8 Power Dissipation and Thermal Characteristics****.*

Table A-4 Operating Conditions

Rating	Symbol	Min	Typ	Max	Unit
I/O, Regulator and Analog Supply Voltage	V_{DD5}	4.5	5	5.25	V
Digital Logic Supply Voltage [1]	V_{DD}	2.35	2.5	2.75	V
PLL Supply Voltage [1]	V_{DDPLL}	2.35	2.5	2.75	V
Voltage Difference VDDX to VDDR and VDDA	Δ_{VDDX}	-0.1	0	0.1	V
Voltage Difference VSSX to VSSR and VSSA	Δ_{VSSX}	-0.1	0	0.1	V
Oscillator	f_{osc}	0.5	-	16	MHz
Bus Frequency	f_{bus}	0.25[2]	-	25	MHz
MC9S12DJ64**C** Operating Junction Temperature Range	T_J	-40	-	100	°C
Operating Ambient Temperature Range [3]	T_A	-40	27	85	°C
MC9S12DJ64**V** Operating Junction Temperature Range	T_J	-40	-	120	°C
Operating Ambient Temperature Range [3]	T_A	-40	27	105	°C
MC9S12DJ64**M** Operating Junction Temperature Range	T_J	-40	-	140	°C
Operating Ambient Temperature Range [3]	T_A	-40	27	125	°C

NOTES:
1. The device contains an internal voltage regulator to generate the logic and PLL supply out of the I/O supply. The given operating range applies when this regulator is disabled and the device is powered from an external source.
2. Some blocks e.g. ATD (conversion) and NVMs (program/erase) require higher bus frequencies for proper operation.
3. Please refer to **Section A.1.8 Power Dissipation and Thermal Characteristics** for more details about the relation between ambient temperature T_A and device junction temperature T_J.

A.1.8 Power Dissipation and Thermal Characteristics

Power dissipation and thermal characteristics are closely related. The user must assure that the maximum operating junction temperature is not exceeded. The average chip-junction temperature (T_J) in °C can be obtained from:

$$T_J = T_A + (P_D \bullet \Theta_{JA})$$

T_J = Junction Temperature, [°C]

NOTES:
1. PLL off
2. At those low power dissipation levels $T_J = T_A$ can be assumed

specifies results in an error of less than 1/2 LSB (2.5mV) at the maximum leakage current. If device or operating conditions are less than worst case or leakage-induced error is acceptable, larger values of source resistance is allowed.

A.2.2.2 Source Capacitance

When sampling an additional internal capacitor is switched to the input. This can cause a voltage drop due to charge sharing with the external and the pin capacitance. For a maximum sampling error of the input voltage ≤ 1LSB, then the external filter capacitor, $C_f \geq 1024 * (C_{INS} - C_{INN})$.

A.2.2.3 Current Injection

There are two cases to consider.

1. A current is injected into the channel being converted. The channel being stressed has conversion values of $3FF ($FF in 8-bit mode) for analog inputs greater than V_{RH} and $000 for values less than V_{RL} unless the current is higher than specified as disruptive condition.
2. Current is injected into pins in the neighborhood of the channel being converted. A portion of this current is picked up by the channel (coupling ratio K), This additional current impacts the accuracy of the conversion depending on the source resistance.
   The additional input voltage error on the converted channel can be calculated as $V_{ERR} = K * R_S * I_{INJ}$, with I_{INJ} being the sum of the currents injected into the two pins adjacent to the converted channel.

Table A-9 ATD Electrical Characteristics

Conditions are shown in **Table A-4** unless otherwise noted							
Num	**C**	**Rating**	**Symbol**	**Min**	**Typ**	**Max**	**Unit**
1	C	Max input Source Resistance	R_S	-	-	1	KΩ
2	T	Total Input Capacitance Non Sampling Sampling	 C_{INN} C_{INS}			 10 22	pF
3	C	Disruptive Analog Input Current	I_{NA}	-2.5		2.5	mA
4	C	Coupling Ratio positive current injection	K_p			10^{-4}	A/A
5	C	Coupling Ratio negative current injection	K_n			10^{-2}	A/A